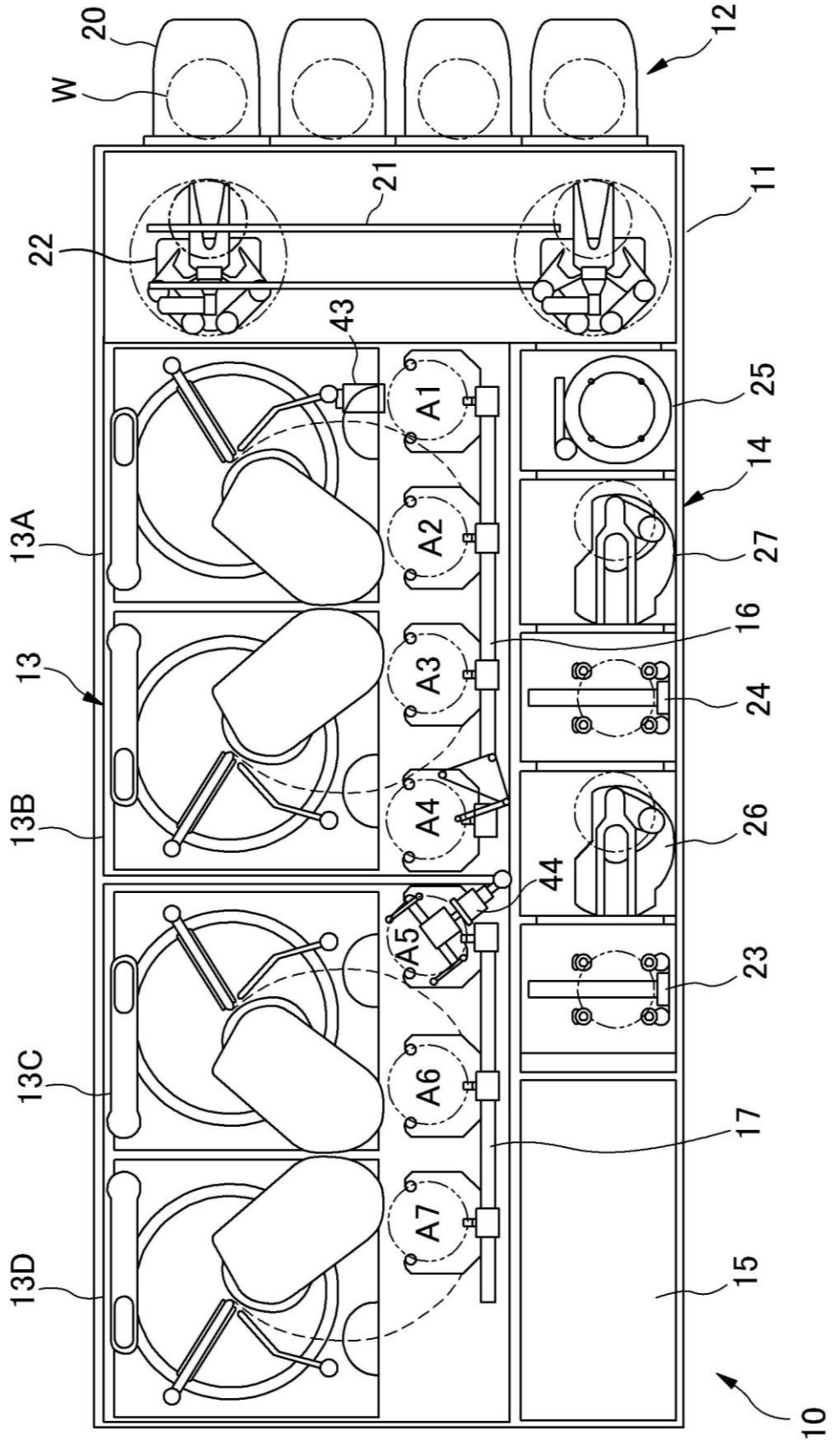

20
W
12
21
11
22
43
A1
25
14
13A
A2
27
16
13
A3
24
13B
A4
26
44
A5
23
13C
A6
17
A7
15
13D
10

FIG. 1

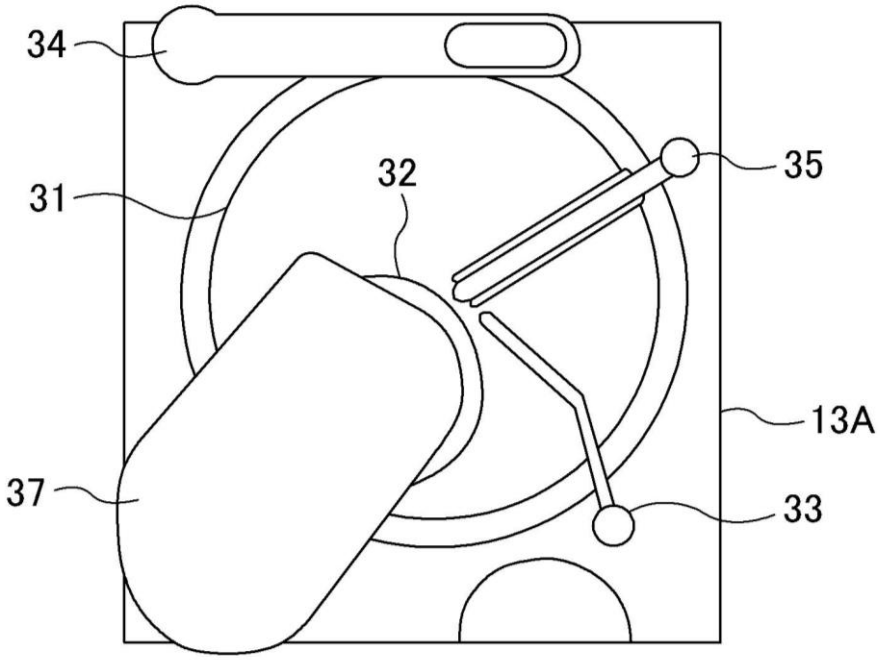


FIG. 2

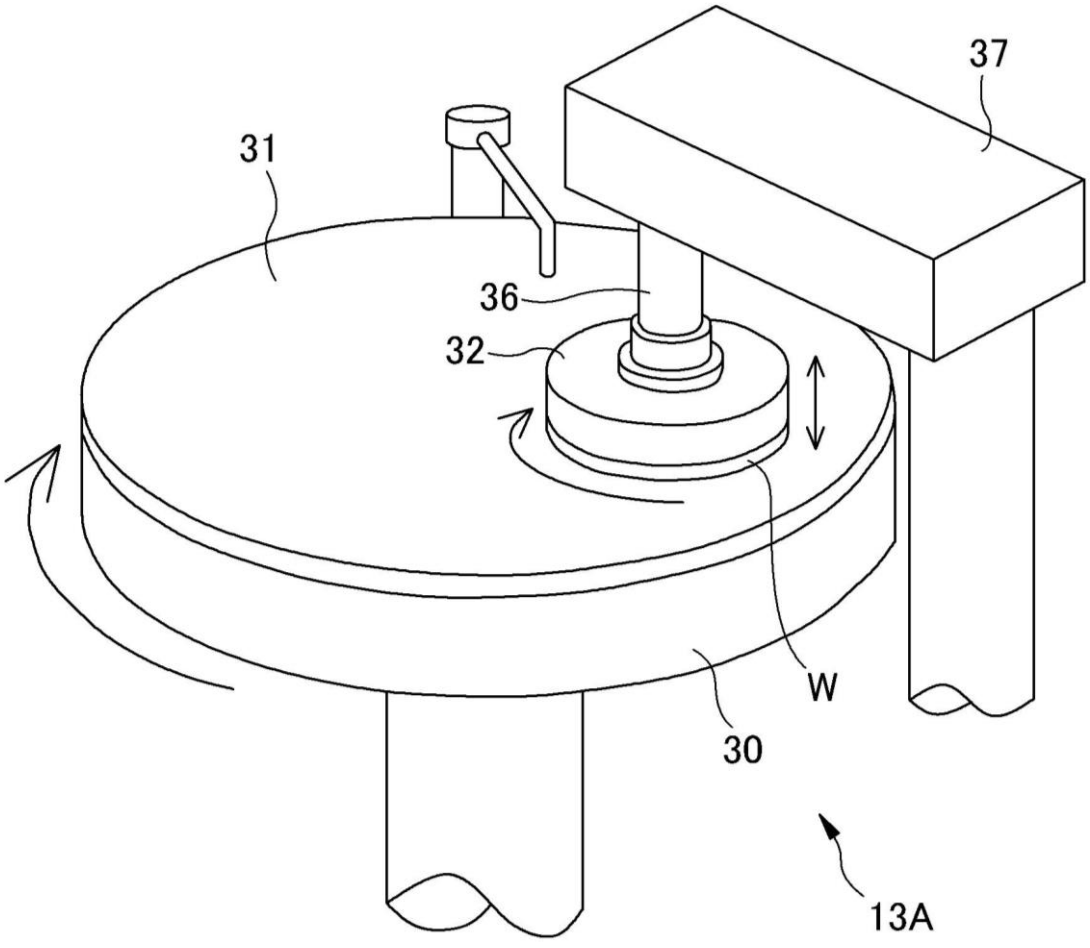


FIG. 3

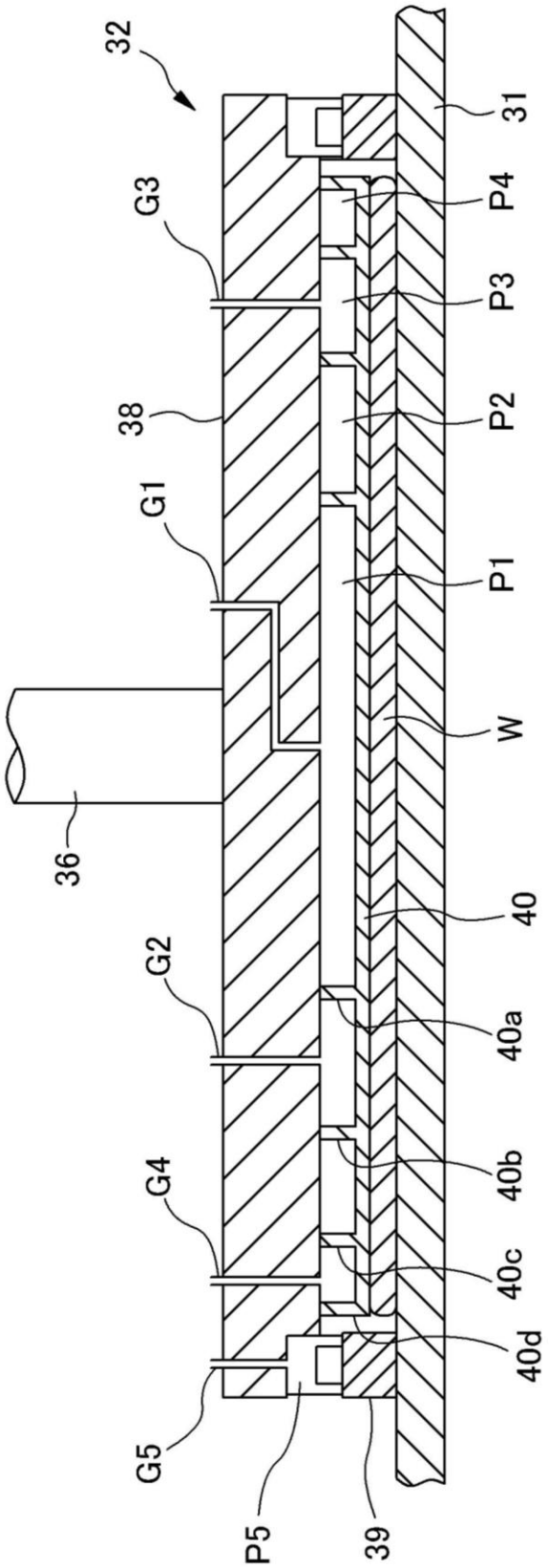


FIG. 4

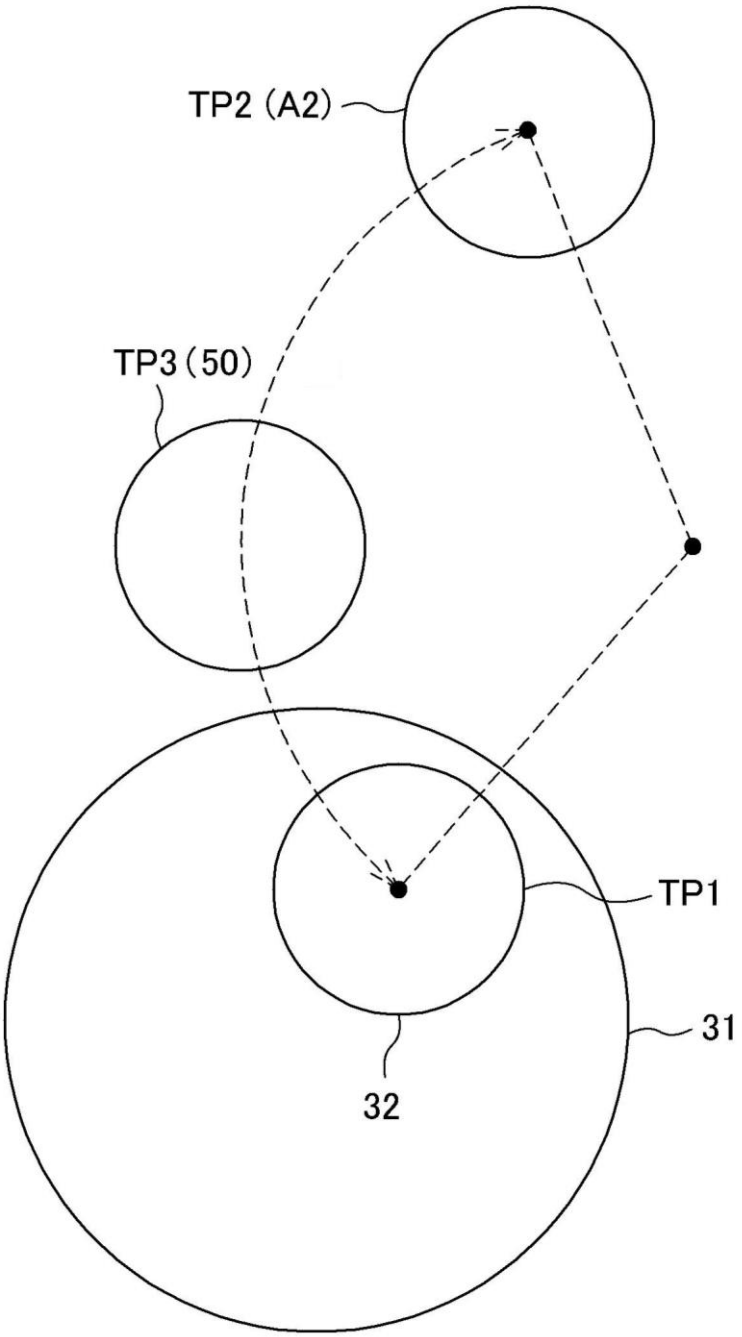


FIG. 5

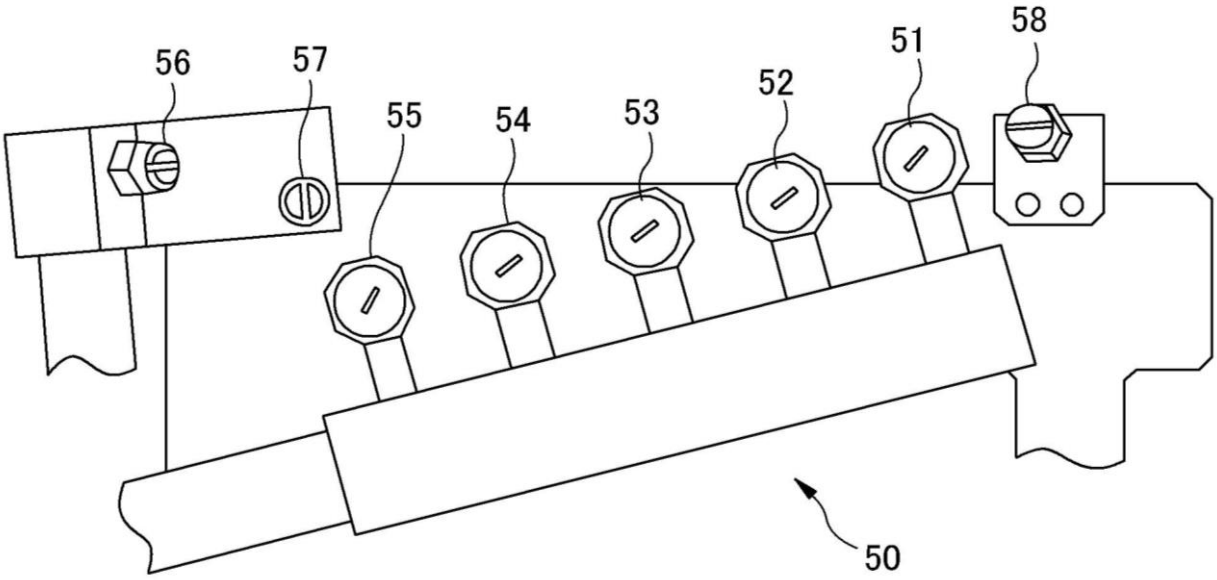

Handover position side
56
57
55
54
53
52
51
58
50
Polishing position side

FIG. 6

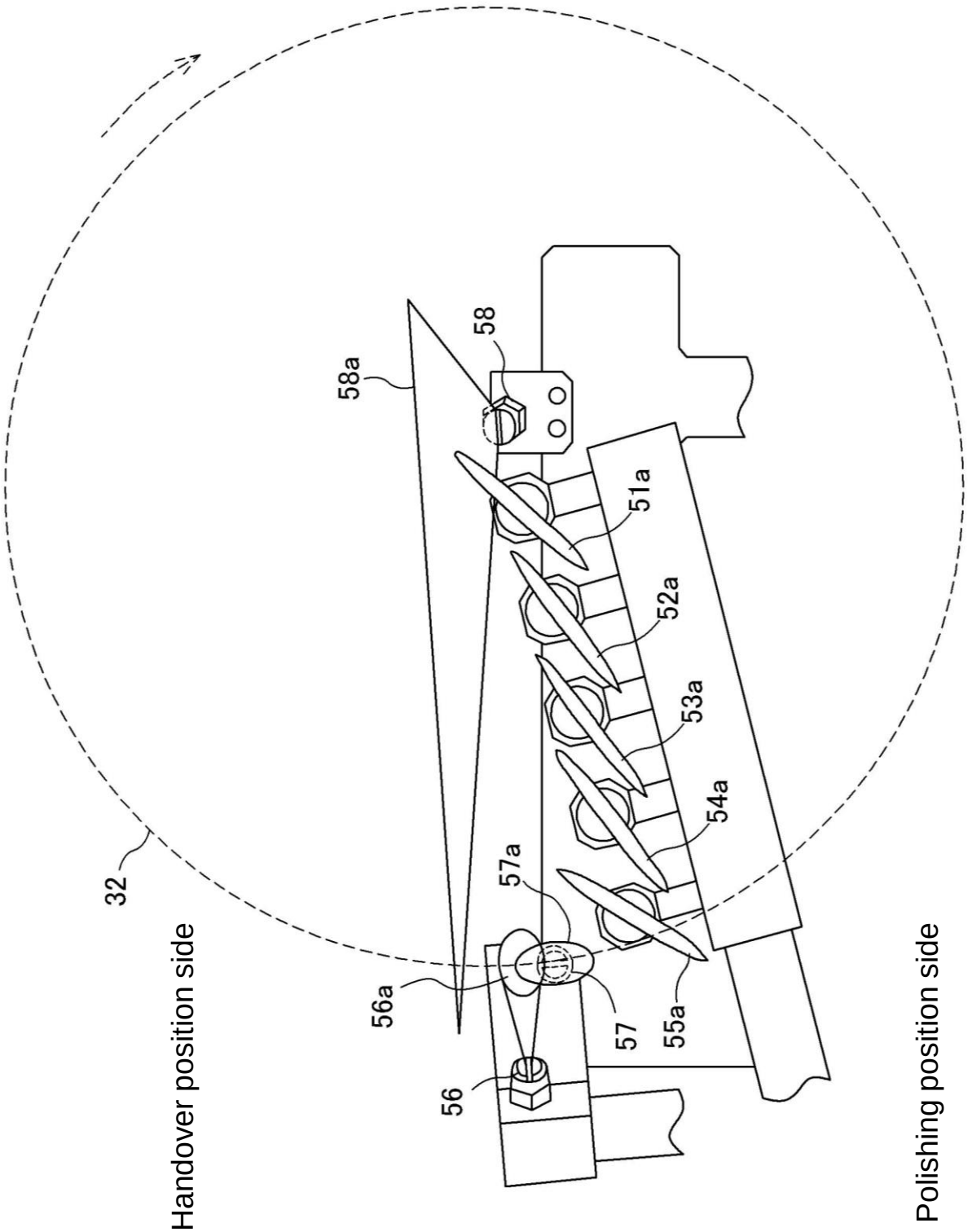

32
Handover position side
Polishing position side
58
58a
51a
52a
53a
54a
55a
56
56a
57
57a

FIG. 7

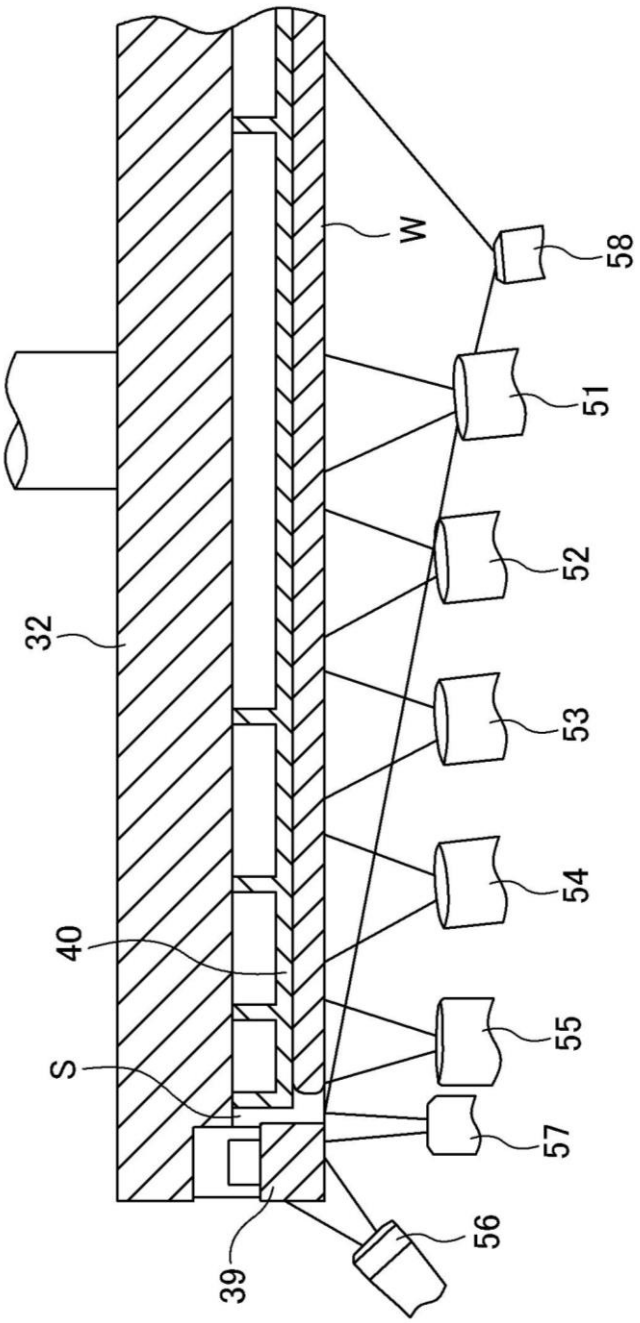


FIG. 8

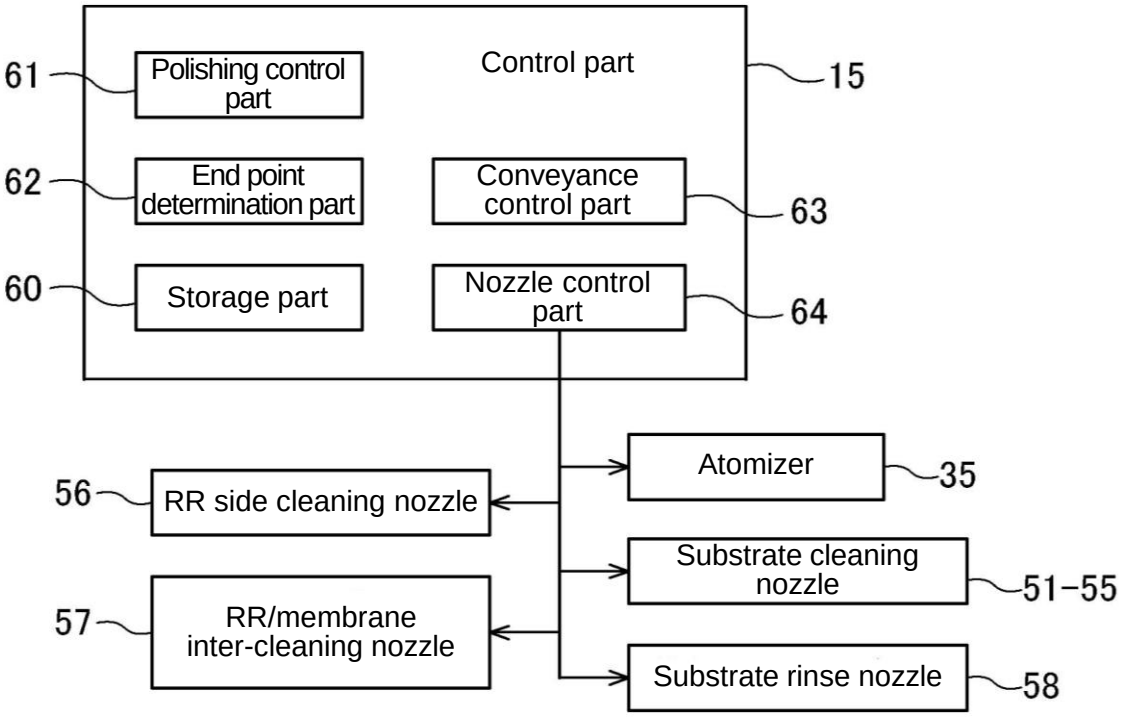

61
Polishing control part
Control part
15
62
End point determination part
Conveyance control part
63
60
Storage part
Nozzle control part
64
Atomizer
35
56
RR side cleaning nozzle
Substrate cleaning nozzle
51–55
57
RR/membrane inter-cleaning nozzle
Substrate rinse nozzle
58

FIG. 9

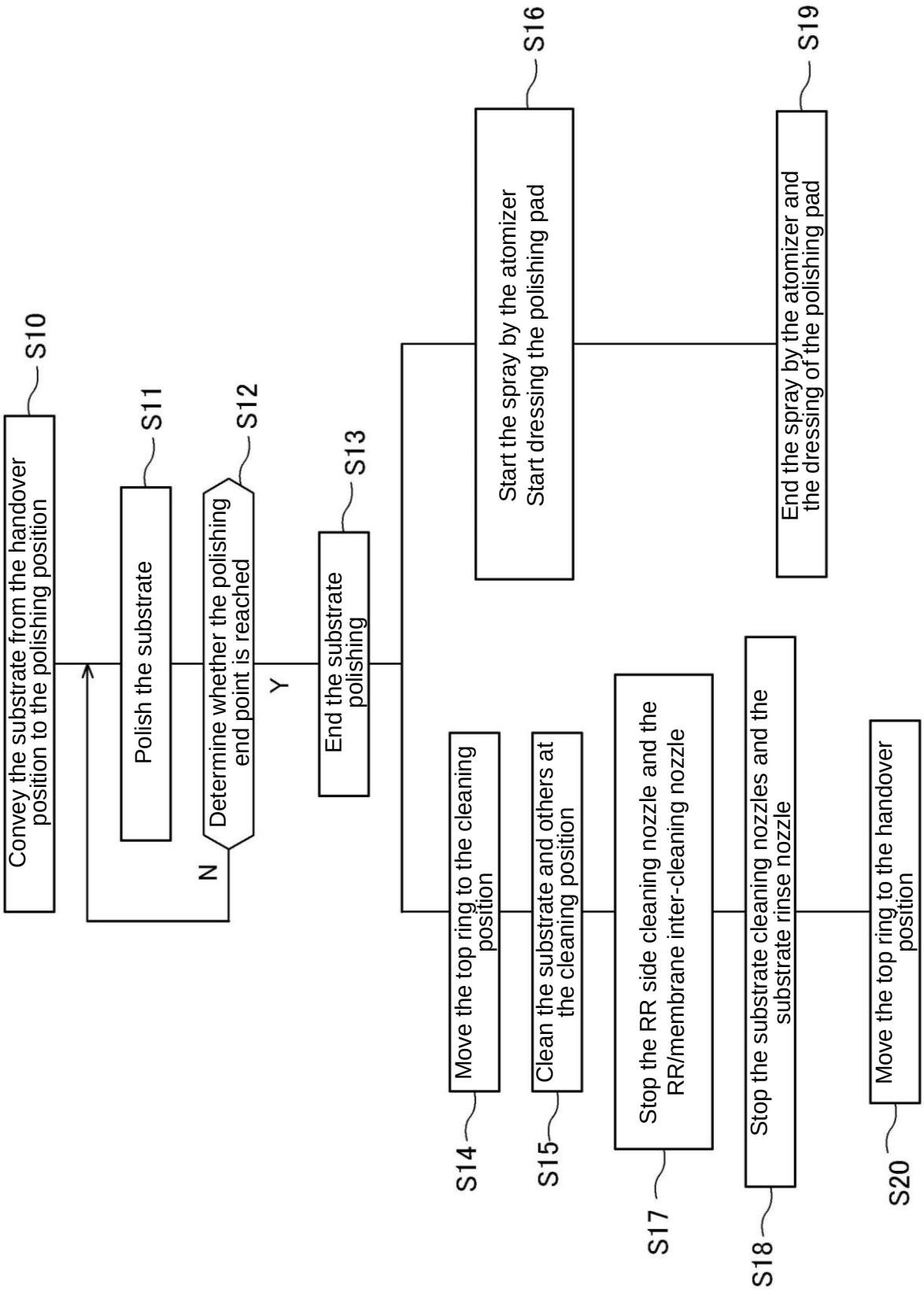

Convey the substrate from the handover position to the polishing position
S10
Polish the substrate
S11
Determine whether the polishing end point is reached
S12
N
Y
End the substrate polishing
S13
Start the spray by the atomizer
Start dressing the polishing pad
S16
End the spray by the atomizer and the dressing of the polishing pad
S19
Move the top ring to the cleaning position
S14
Clean the substrate and others at the cleaning position
S15
Stop the RR side cleaning nozzle and the RR/membrane inter-cleaning nozzle
S17
Stop the substrate cleaning nozzles and the substrate rinse nozzle
S18
Move the top ring to the handover position
S20

FIG. 10